

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Batz, Jr., et al.)
)
 For: Methods for Plating)
 Semiconductor Workpieces)
 Using a Workpiece-Engaging)
 Electrode Assembly with)
 Sealing Boot)
)
 Serial No.: 09/390501)
)
 Filed: September 3, 1999)
)
 Examiner: HICKS)
)
 Art Unit: 1741)

SAD

#2A

11-3-99

PRELIMINARY AMENDMENT

Box Patent Application
 Assistant Commissioner for Patents
 Washington, D.C. 20231

Dear Sir:

Please preliminarily amend the application filed herewith, as follows:

IN THE SPECIFICATION:

Please amend the specification as follows:

On page 1, insert before line 1 -- [This is a continuation application of U.S. patent

application Serial No. 08/940,685 filed September 30, 1997, entitled METHODS FOR
 PLATING SEMICONDUCTOR WORKPIECES USING WORKPIECE-ENGAGING
 ELECTRODE ASSEMBLY WITH SEALING BOOT.

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